TOSHIBA Zener Diode Silicon Diffused Type

CMZB12 to CMZB51

○ Surge absorber

• Average power dissipation : P = 1 W

• Zener voltage $V_Z = 12 \text{ to } 51 \text{ V}$

• Suitable for high-density board assembly due to the use of a small surface-mount package, $M\text{-}FLAT^{TM}$

Absolute Maximum Ratings (Ta = 25°C)

| Characteristics | Sym bol | Rating | Unit |
|---------------------------|------------------|------------|------|
| Power dissipation | Р | 1 (Note 1) | W |
| Junction temperature | Tj | -40 to 150 | °C |
| Storage temperature range | T _{stg} | -40 to 150 | ζc(|

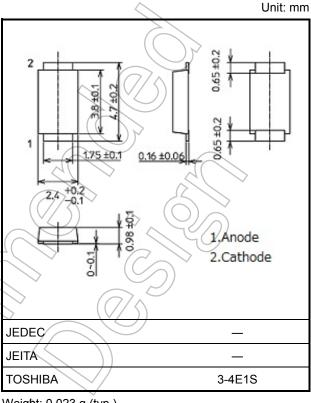
Note 1: $Ta = 40^{\circ}C$

Device mounted on a glass-epoxy board

Board size : $50 \text{ mm} \times 50 \text{ mm}$

Soldering size : $6 \text{ mm} \times 6 \text{ mm}$

Board thickness : 1.6 mm

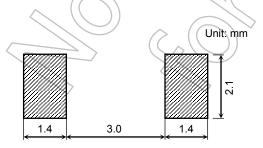


Weight: 0.023 g (typ.)

Note 2: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature / current / voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Land Pattern Dimensions (reference only)

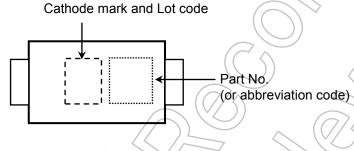


Start of commercial production 2005-09

Electrical Characteristics (Ta = 25°C)

| | Zener Voltage Vz (V) | | | Zener Impedance $r_d(\Omega)$ | | Temperature Coefficient Of Zener | | Forward Voltage V _F (V) | | Reverse Current I _R (μA) | | |
|--------|-------------------------|------|------|--|-----|--|-------|---------------------------------------|-----|--|------|---------------------------------------|
| Type | | | | Measure- | | Measure- | αT (m | ıV/°C) | | Measure- | | Measure- |
| | Min | Тур. | Max | ment Current I _Z (mA) | Max | ment Current I _Z (mA) | Тур. | Max | Max | ment Current I _F (A) | Max | ment Voltage V _R (V) |
| CMZB12 | 10.8 | 12 | 13.2 | 10 | 30 | 10 | 8 | 13 | 1.2 | 0.2 | 10 | 8 |
| CMZB13 | 11.7 | 13 | 14.3 | 10 | 30 | 10 | 9 | 14 | 1.2 | 0.2 | 10 | 9 |
| CMZB15 | 13.5 | 15 | 16.5 | 10 | 30 | 10 | 11 | 17 | 1.2 | 0.2 | 10 | 10 |
| CMZB18 | 16.2 | 18 | 19.8 | 10 | 30 | 10 | 14 | 23 | 1.2 | 0.2 | 10 | 13 |
| CMZB20 | 18.0 | 20 | 22.0 | 10 | 30 | 10 | 16 | 26 | 1.2 | 0.2 | 10 | 14 |
| CMZB24 | 21.6 | 24 | 26.4 | 10 | 30 | 10 | 20 | 32 | 1.2 | 0.2 | 10 | 17 |
| CMZB27 | 24.3 | 27 | 29.7 | 10 | 30 | 10 | 23 | 36 | 1.2 | 0.2 | 10 | 19 |
| CMZB30 | 27.0 | 30 | 33.0 | 10 | 30 | 10 | 25 | 40 | 1.2 | 0.2 | 10 | 21 |
| CMZB33 | 29.7 | 33 | 36.3 | 10 | 30 | 10 | 26 | /41 | 1.2 | 0.2 | 10 | 26.4 |
| CMZB36 | 32.4 | 36 | 39.6 | 9 | 30 | 9 | 28 | <i>4</i> 5 | 1.2 | 0.2 | 10 | 28.8 |
| CMZB39 | 35.1 | 39 | 42.9 | 8 | 35 | 8 | 30 | 48 | 1.2 | 0.2 | //10 | 31.2 |
| CMZB43 | 38.7 | 43 | 47.3 | 7 | 40 | 7.(| 33 | 53 | 1/2 | 0.2 | 10 | 34.4 |
| CMZB47 | 42.3 | 47 | 51.7 | 6 | 65 | 6 | 38 | 60 | 1.2 | 0.2 | 10 | 37.6 |
| CMZB51 | 45.9 | 51 | 56.1 | 6 | 65 | 6 | 43 | 68 | 1.2 | 0.2 | 10 | 40.8 |

1. Marking



| Abbreviation Code | Part No. | Abbreviation Code | Part No. |
|----------------------|----------|-------------------|----------|
| B12 | CMZB12 | B30 | CMZB30 |
| B13 | CMZB13 | B33 | CMZB33 |
| B15 | CMZB15 | B36 | CMZB36 |
| B18 | CMZB18 | B39 | CMZB39 |
| B20 | CMZB20 | B43 | CMZB43 |
| B24 | CMZB24 | B47 | CMZB47 |
| B27 | CMZB27 | B51 | CMZB51 |

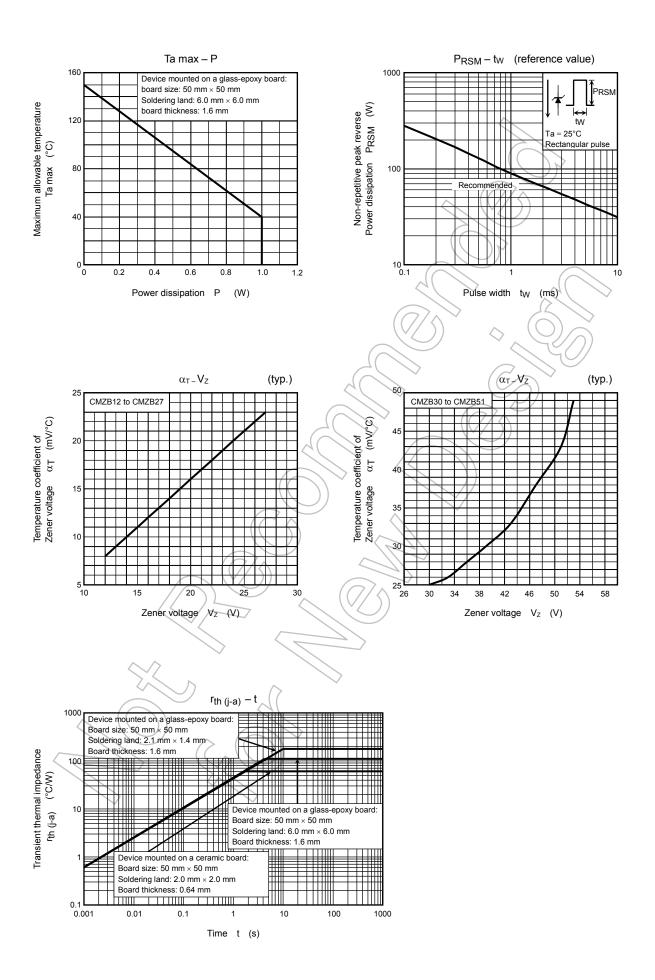
Handling Precaution

1) The absolute maximum ratings of a semiconductor device are a set of ratings that must not be exceeded, even for a moment. Do not exceed any of these ratings. The following are the general derating methods that we recommend when you design a circuit with a device.

P: We recommend that the worst case power dissipation be no greater than 50% of the absolute maximum rating of power dissipation. Carry out adequate heat design.

 P_{RSM} : We recommend that a device be used within the recommended area in the figure, P_{RSM} -tw.

- T_j : Derate this rating when using a device in order to ensure high reliability. We recommend that the device be used at T_j of below 120°C.
- 2) Thermal resistance between junction and ambient fluctuates depending on the device's mounting condition. When using a device, design a circuit board and a soldering land size to match the appropriate thermal resistance value.
- 3) Please refer to the Rectifiers databook for further information.



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